ABSTRACT

An interconnect assembly includes a number of interconnects combined in a preferably planar dielectric carrier frame having resilient portions acting as spring members in conjunction with their respective interconnect's rotational displacement during operational contacting. Each interconnect is fabricated as a see-saw structure pivoting around a rotation axis that substantially coincides with a symmetry plane of the torsion features provided by the resilient portion. The torsion features protrude towards and adhere to a central portion of the see-saw interconnect such that an angular movement of the interconnect is resiliently opposed by the torsion feature and the resilient portion. The torsion features and interconnects may be independently optimized to provide the interconnect with maximum stiffness and a maximum deflection at same time.